



**Job description:** UniSCool is a spin-off of the Universities of Lleida and Sherbrooke that develops advanced direct-to-chip liquid cooling systems for electronic applications, focused mainly on the efficient thermal management of data centres.

We are looking to increase our R&D team to work on the development and validation of advanced liquid cooling solutions, seeking a highly skilled and motivated professional specializing in mechanical and thermal engineering.

**Job title:** R&D Hardware Engineer

**Responsibilities:**

- Design and fabrication of prototypes.
- Validation of current and new thermal management solutions at laboratory.
- Experimental assessment of KPIs
- Numerical thermohydraulic simulations of cooling systems.
- Implementation of reliability tests
- Pilots' implementation and monitoring

**Job location:** Lleida, Catalonia, Spain

**Work schedule:** full time, 40 hours/week, flexible hours.

**Job requirements:**

- Degree or master's degree in engineering.
- Knowledge in thermofluidics.
- Experience in 3D printing will be valued.
- Experience in experimental works will be valued.
- Knowledge in materials engineering, materials science or similar will be valued.
- Knowledge of thermal management of electronic systems will be valued.
- Knowledge of CFD analysis will be valued.
- Knowledge of Labview will be valued.
- Knowledge of electronic equipment and data centre infrastructures will be valued.
- Fluent English.

**Skills:**

- Communication skills.
- Hands-on skills.
- Practical mindset.
- Result oriented.

If you meet these qualifications and are excited about the opportunity to work on innovative projects in a dynamic environment, we would love to hear from you. Send your **CV** to [jerome.barrau@uniscool.tech](mailto:jerome.barrau@uniscool.tech)



[www.uniscool.tech](http://www.uniscool.tech)

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